

**AMENDMENTS TO THE CLAIMS**

Please cancel claims 8 and 9. The following is a listing of claims as they currently appear in the case:

1. (Original) An electronics assembly comprising:  
a heat generating component;  
a heat sink positioned to define a gap between said heat generating component and said heat sink;  
at least one pre-cured a first thermal adhesive member positioned within said gap creating a physical barrier between said heat generating component and said heat sink; and  
a post-cured thermal adhesive member filling said gap.
2. (Original) An electronics assembly as described in claim 1 wherein said heat generating component is an electrical component.
3. (Original) An electronics assembly as described in claim 1 wherein said at least one pre-cured thermal adhesive member is formed using droplets of thermal adhesive.
4. (Original) An electronics assembly as described in claim 1 wherein said at least one pre-cured thermal adhesive member is affixed to said heat generating component prior to assembly.
5. (Original) An electronics assembly as described in claim 1 wherein said at least one pre-cured thermal adhesive member is affixed to said heat sink prior to assembly.

6. (Original) An electronics assembly as described in claim 1 further comprising:

a substrate; and

at least one clamping mechanism attaching said substrate to said heat sink.

7. (Original) An electronics assembly as described in claim 1 wherein said heat sink is a metal case.

8. (Cancelled).

9. (Cancelled).

10. (Original) An electronics assembly as described in claim 1 wherein said at least one pre-cured thermal adhesive member includes dots of equal height.

11. (Allowed) A method of applying thermal adhesive to an electronics assembly comprising:

forming a plurality of pre-cure thermal adhesive members;

curing said plurality of pre-cure thermal adhesive members;

applying a post-cure thermal adhesive;

assembling an electronics assembly including a heat generating component and a heat sink such that said plurality of pre-cure thermal adhesive members and said post-cure thermal adhesive are positioned within a gap formed between said heat generating component and said heat sink; and

curing said post-cure thermal adhesive.

12. (Allowed) A method as described in claim 11 wherein said plurality of pre-cure thermal adhesive members are formed on said heat generating component.

13. (Allowed) A method as described in claim 11 wherein said plurality of pre-cure thermal adhesive members are formed in said heat sink.

14. (Allowed) A method as described in claim 11 wherein said heat generating component is an electrical component.

15. (Allowed) A method as described in claim 11 wherein said forming a plurality of pre-cure thermal adhesive members includes forming droplets of pre-cure thermal adhesive.

16. (Allowed) A method as described in claim 11 wherein said post-cure thermal adhesive is applied to said heat generating component.

17. (Allowed) A method as described in claim 11 wherein said post-cure thermal adhesive is applied to said heat sink.